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**80MHz, High Slew Rate, High Output Current, Video Operational Amplifier**

The HA-2842 is a wideband, high slew rate, operational amplifier featuring an outstanding combination of speed, bandwidth, and output drive capability. This amplifier's performance is further enhanced through stable operation down to closed loop gains of +2, the inclusion of offset null controls, and by its excellent video performance.

The capabilities of the HA-2842 are ideally suited for high speed cable driver circuits, where low closed loop gains and high output drive are required. With a 6MHz full power bandwidth, this amplifier is well suited for high frequency signal conditioning circuits and video amplifiers. Gain flatness of 0.035dB, combined with differential gain and phase specifications of 0.02%, and 0.03 degrees, respectively, make the HA-2842 ideal for component and composite video applications.

A zener/nichrome based reference circuit, coupled with advanced laser trimming techniques, yields a supply current with a low temperature coefficient and low lot-to-lot variability. For example, the average I<sub>CC</sub> variation from 85°C to -40°C is <600µA (±2%), while the standard deviation of the I<sub>CC</sub> distribution is <0.1mA (0.8%) at 25°C. Tighter I<sub>CC</sub> control translates to more consistent AC parameters ensuring that units from each lot perform the same way, and easing the task of designing systems for wide temperature ranges. Critical AC parameters, Slew Rate and Bandwidth, each vary by less than ±5% over the industrial temperature range (see Typical Performance Curves)

**Part Number Information.**

PART NUMBER (BRAND)	TEMP. RANGE (°C)	PACKAGE	PKG. DWG. #
HA9P2842-5 (H2842F5)	0 to 75	8 Ld SOIC	M8.15

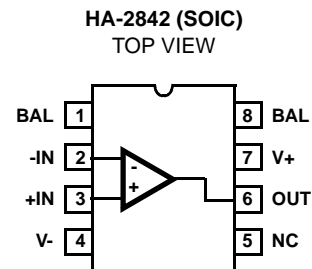
**Features**

- Stable at Gains of 2 or Greater
- Low AC Variability Over Process and Temperature
- Gain Bandwidth . . . . . 80MHz
- Gain Flatness to 10MHz. . . . . 0.035dB
- High Slew Rate. . . . . 400V/µs
- High Output Current (Min) . . . . . 100mA
- Differential Gain/Phase . . . . . 0.02%/0.03 Degrees
- Low Supply Current (Max) . . . . . 15mA
- Enhanced Replacement for AD842

**Applications**

- Pulse and Video Amplifiers
- Wideband Amplifiers
- Coaxial Cable Drivers
- Fast Sample-Hold Circuits
- High Frequency Signal Conditioning Circuits

**Pinout**



**Absolute Maximum Ratings**

Voltage Between V+ and V- Terminals . . . . . 35V  
 Differential Input Voltage . . . . . 6V  
 Output Current (Notes 3, 4) . . . . . 125mA  
 . . . . . 100mA (50% Duty Cycle)

**Operating Conditions**

Temperature Range  
 HA-2842-5 . . . . . 0°C to 75°C  
 Recommended Supply Voltage Range . . . . . ±6.5V to ±15V

**Thermal Information**

Thermal Resistance (Typical, Note 2)  $\theta_{JA}$  (°C/W)  
 8 Lead SOIC Package . . . . . 160  
 Maximum Junction Temperature (Die) . . . . . 175°C  
 Maximum Junction Temperature (Plastic Package, Note 1) . . . . . 150°C  
 Maximum Storage Temperature Range . . . . . -65°C to 150°C  
 Maximum Lead Temperature (Soldering 10s) . . . . . 300°C  
 (Lead Tips Only)

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

**NOTES:**

1. Maximum power dissipation, including output load, must be designed to maintain the maximum junction temperature below 150°C for plastic packages. By using Application Note AN556 on Safe Operating Area equations, along with the packaging thermal resistances listed in the Thermal Information section, proper load conditions can be determined.
2.  $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.
3.  $V_O = \pm 5V$ ,  $R_L$  Unconnected, Duty cycle  $\leq 50\%$ . For information about using high output current amplifiers, please refer to Application Note AN556 (Thermal Safe-Operating-Areas For High Current Op Amps), and the "Power Dissipation Considerations" section in the "Application Information" section of this datasheet.
4. Maximum continuous (100% Duty Cycle) output current is 50mA. For currents >50mA, Duty Cycle must be derated accordingly.

**Electrical Specifications**  $V_{SUPPLY} = \pm 15V$ ,  $R_L = 1k\Omega$ ,  $C_L \leq 10pF$ , Unless Otherwise Specified

PARAMETER	TEST CONDITIONS	TEMP (°C)	HA-2842-5			UNITS
			MIN	TYP	MAX	
<b>INPUT CHARACTERISTICS</b>						
Offset Voltage (Note 10)		25	-	1	3	mV
		Full	-	-	6	mV
Average Offset Voltage Drift		Full	-	13	-	$\mu V/^\circ C$
Bias Current (Note 10)		25	-	5	10	$\mu A$
		Full	-	-	15	$\mu A$
Average Bias Current Drift		Full	-	20	-	$nA/^\circ C$
Offset Current		25	-	0.5	1.0	$\mu A$
		Full	-	-	1.5	$\mu A$
Average Offset Current Drift		Full	-	1.3	-	$nA/^\circ C$
Input Resistance		25	-	170	-	$k\Omega$
Input Capacitance		25	-	1	-	pF
Common Mode Range		Full	±10	-	-	V
Input Noise Voltage	10Hz to 1MHz	25	-	16	-	$\mu V_{RMS}$
Input Noise Voltage Density	$f = 1kHz$ , $R_{SOURCE} = 0\Omega$	25	-	16	-	$nV/\sqrt{Hz}$
Input Noise Current (Note 10)	$f = 1kHz$ , $R_{SOURCE} = 100k\Omega$	25	-	2	-	$pA/\sqrt{Hz}$
<b>TRANSFER CHARACTERISTICS</b>						
Large Signal Voltage Gain	$V_O = \pm 10V$	25	50	100	-	$kV/V$
		Full	30	60	-	$kV/V$
Common-Mode Rejection Ratio (Note 10)	$V_{CM} = \pm 10V$	Full	80	110	-	dB
Minimum Stable Gain		25	2	-	-	$V/V$
Gain Bandwidth Product (Note 10)	$A_{VCL} = 100$	25	-	80	-	MHz
Gain Flatness to 10MHz (Note 10)	$R_L \geq 75\Omega$	25	-	±0.035	-	dB

## HA-2842

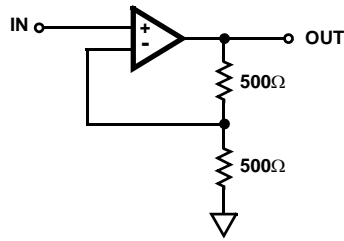
### Electrical Specifications $V_{\text{SUPPLY}} = \pm 15\text{V}$ , $R_L = 1\text{k}\Omega$ , $C_L \leq 10\text{pF}$ , Unless Otherwise Specified (Continued)

PARAMETER	TEST CONDITIONS	TEMP (°C)	HA-2842-5			UNITS
			MIN	TYP	MAX	
<b>OUTPUT CHARACTERISTICS</b>						
Output Voltage Swing (Note, 10)	$V_O = \pm 10\text{V}$	Full	$\pm 10$	$\pm 11$	-	V
Output Current (Note 10)	(Note 3)	Full	100	-	-	mA
Output Resistance		25	-	8.5	-	$\Omega$
Full Power Bandwidth (Note 6)	$V_O = \pm 10\text{V}$	25	5.2	6	-	MHz
Differential Gain (Note 10)	(Note 5)	25	-	0.02	-	%
Differential Phase (Note 10)	(Note 5)	25	-	0.03	-	Degrees
Harmonic Distortion (Note 10)	$V_O = 2V_{\text{P-P}}$ , $f = 1\text{MHz}$ , $A_V = 2$	25	-	>81	-	dBc
<b>TRANSIENT RESPONSE (Note 7)</b>						
Rise Time		25	-	4	-	ns
Overshoot		25	-	25	-	%
Slew Rate (Notes 9, 10)	$A_V = +2$	25	325	400	-	V/ $\mu\text{s}$
Settling Time	10V Step to 0.1%	25	-	100	-	ns
<b>POWER REQUIREMENTS</b>						
Supply Current (Note 10)		25	-	14.2	-	mA
		Full	-	14.3	15	mA
Power Supply Rejection Ratio (Note 10)	(Note 8)	Full	70	80	-	dB

**NOTES:**

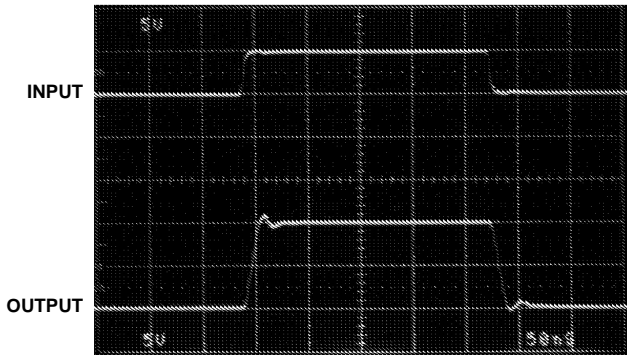
5. Differential gain and phase are measured with a VM700A video tester, using a NTC-7 composite VITS.  $R_F = R_1 = 1\text{k}\Omega$ ,  $R_L = 700\Omega$ .
6. Full Power Bandwidth guaranteed based on slew rate measurement using  $\text{FPBW} = \frac{\text{Slew Rate}}{2\pi V_{\text{PEAK}}}$ ;  $V_{\text{PEAK}} = 10\text{V}$ .
7. Refer to Test Circuits section of this data sheet.
8.  $V_{\text{SUPPLY}} = \pm 10\text{V}$  to  $\pm 20\text{V}$ .
9. This parameter is not tested. The limits are guaranteed based on lab characterization and reflect lot-to-lot variation.
10. See "Typical Performance Curves" for more information.

Test Circuits and Waveforms



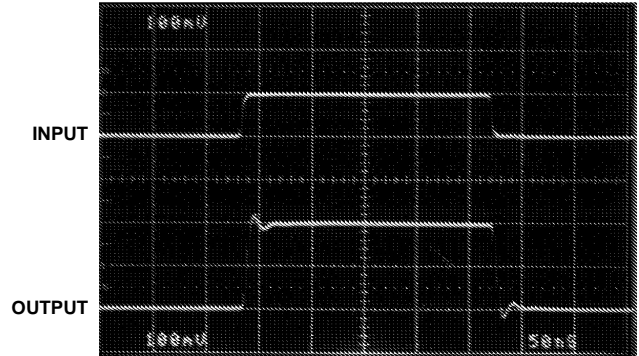
- NOTES:
11.  $V_S = \pm 15V$ .
  12.  $A_V = +2$ .
  13.  $C_L \leq 10pF$

TEST CIRCUIT



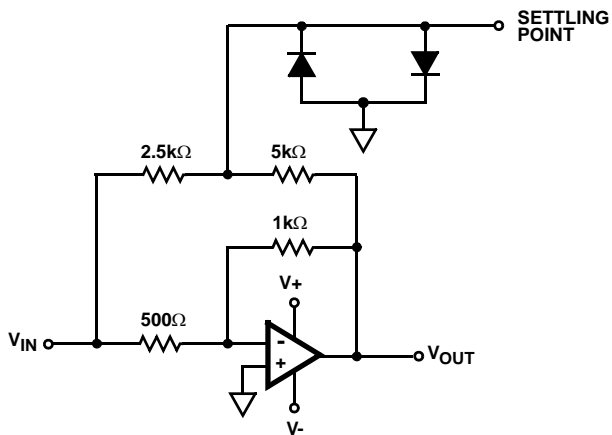
Input = 5V/Div., Output = 5V/Div., 50ns/Div.

LARGE SIGNAL RESPONSE



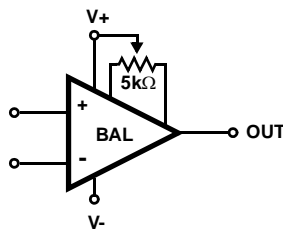
Input = 100mV/Div., Output = 100mV/Div., 50ns/Div.

SMALL SIGNAL RESPONSE



SETTLING TIME TEST CIRCUIT

- NOTES:
14.  $A_V = -2$ .
  15. Feedback and summing resistors must be matched (0.1%).
  16. HP5082-2810 clipping diodes recommended.
  17. Tektronix P6201 FET probe used at settling point.
  18. For 0.01% settling time, heat sinking is suggested to reduce thermal effects and an analog ground plane with supply decoupling is suggested to minimize ground loop errors.



SUGGESTED OFFSET VOLTAGE ADJUSTMENT

**Application Information**

The Intersil HA-2842 is a state of the art monolithic device which also approaches the “ALL-IN-ONE” amplifier concept. This device features an outstanding set of AC parameters augmented by excellent output drive capability providing for suitable application in both high speed and high output drive circuits.

Primarily intended to be used in balanced 50Ω and 75Ω coaxial cable systems as a driver, the HA-2842 could also be used as a power booster in audio systems as well as a power amp in power supply circuits. This device would also be suitable as a small DC motor driver.

**Prototyping Guidelines**

For best overall performance in any application, it is recommended that high frequency layout techniques be used. This should include:

1. Mounting the device through a ground plane.
2. Connecting unused pins (NC) to the ground plane.
3. Mounting feedback components on Teflon standoffs and/or locating these components as close to the device as possible.
4. Placing power supply decoupling capacitors from device supply pins to ground.

**Power Dissipation Considerations**

At high output currents, especially with the 8 lead SOIC package, care must be taken to ensure that the Maximum Junction Temperature ( $T_J$ , see “Absolute Maximum Ratings” table) isn’t exceeded. As an example consider the HA-2842 in the SOIC package, with a required output current of 50mA at  $V_{OUT} = 10V$  with  $\pm 15V$  supplies. The power dissipation is the quiescent power ( $450mW = 30V \times 15mA$ ) plus the power dissipated in the output stage ( $P_{OUT} = 250mW = 50mA \times (15V - 10V)$ ), or a total of 700mW. The thermal resistance ( $\theta_{JA}$ ) of the SOIC package is  $157^\circ C/W$ , which increases the junction temperature by  $110^\circ C$  over the ambient temperature ( $T_A$ ). Remaining below  $T_{JMAX}$  requires that  $T_A$  be restricted to  $\leq 40^\circ C$  ( $150^\circ C - 110^\circ C$ ). Heatsinking would be required for operation at ambient temperatures greater than  $40^\circ C$ .

**MAX  $P_{OUT}$  WITHOUT HEATSINK ( $V_S = \pm 15V$ )**

$T_A$	8 LEAD SOIC ( $\theta_{JA} = 157^\circ C/W$ )
$85^\circ C$	Heatsink Required
$70^\circ C$	60mW
$25^\circ C$	350mW

Allowable output power can be increased by decreasing the quiescent dissipation via lower supply voltages.

For more information please refer to Application Note AN556, Thermal Safe Operating Areas for High Current Op Amps.

**Typical Performance Curves**  $T_A = 25^\circ C$ ,  $V_{SUPPLY} = \pm 15V$ ,  $R_L = 1k\Omega$ ,  $C_L < 10pF$ , Unless Otherwise Specified

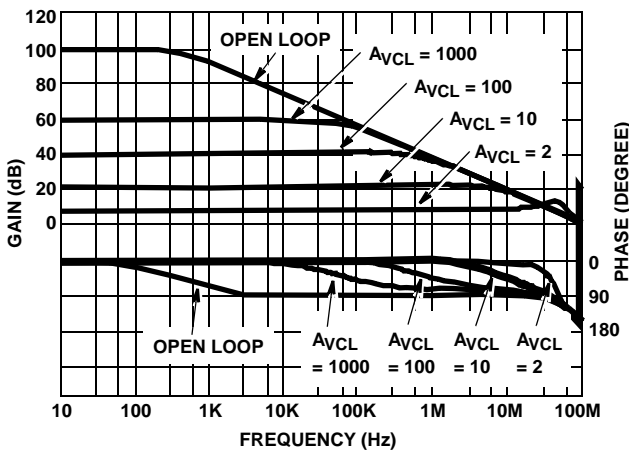


FIGURE 1. FREQUENCY RESPONSE FOR VARIOUS GAINS

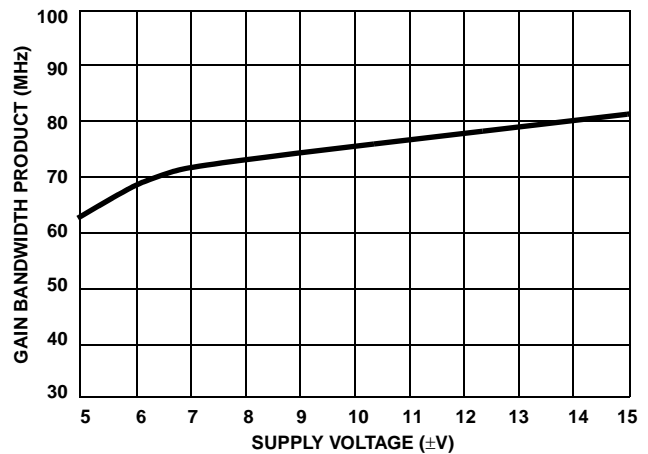


FIGURE 2. GAIN BANDWIDTH PRODUCT vs SUPPLY VOLTAGE

**Typical Performance Curves**  $T_A = 25^\circ\text{C}$ ,  $V_{\text{SUPPLY}} = \pm 15\text{V}$ ,  $R_L = 1\text{k}\Omega$ ,  $C_L < 10\text{pF}$ , Unless Otherwise Specified (Continued)

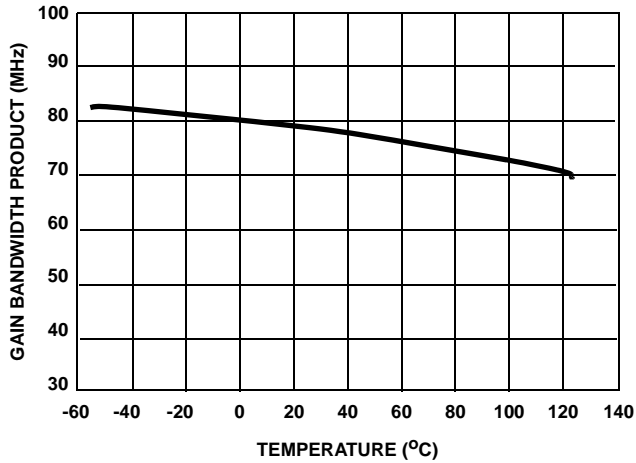


FIGURE 3. GAIN BANDWIDTH PRODUCT vs TEMPERATURE

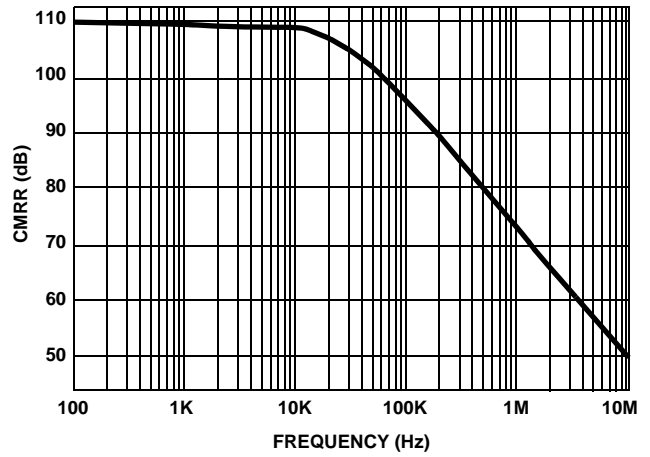


FIGURE 4. CMRR vs FREQUENCY

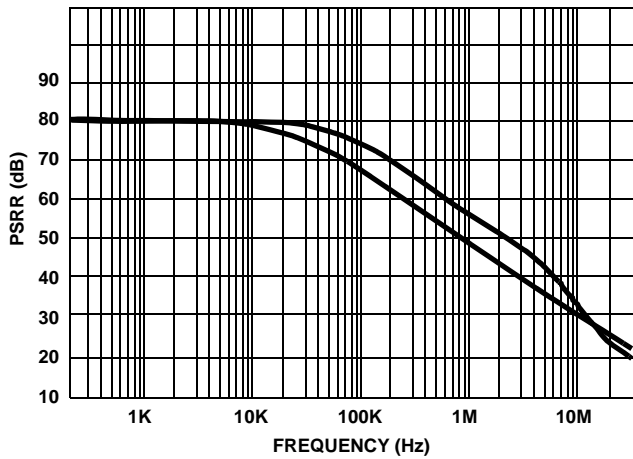


FIGURE 5. PSRR vs FREQUENCY

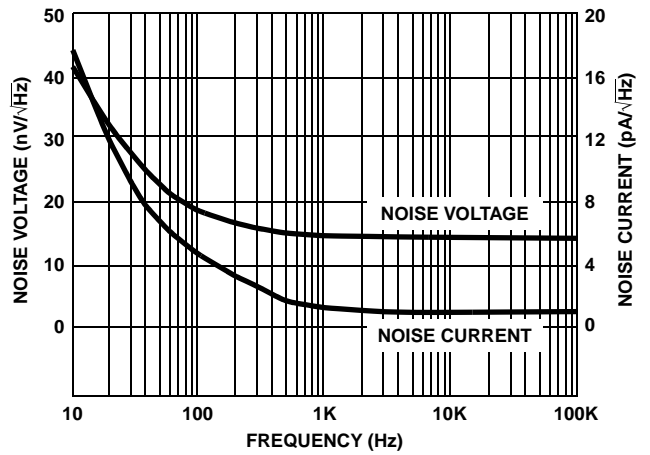


FIGURE 6. INPUT NOISE vs FREQUENCY

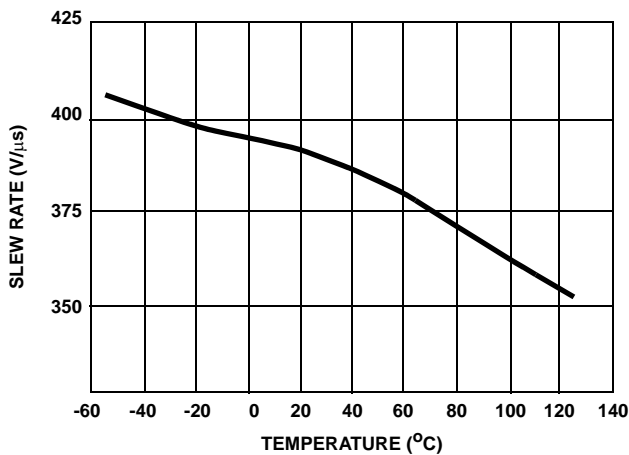


FIGURE 7. SLEW RATE vs TEMPERATURE

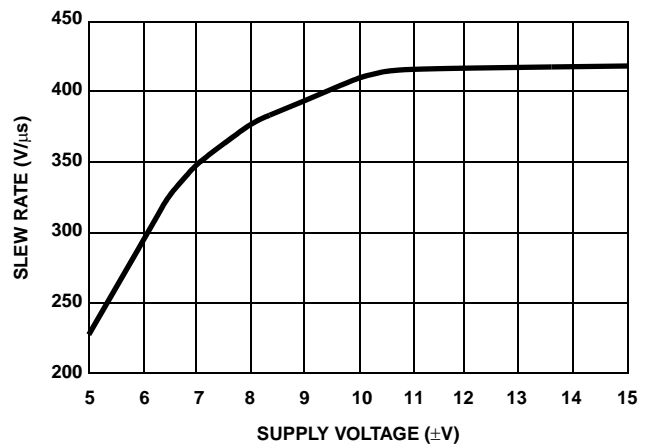


FIGURE 8. SLEW RATE vs SUPPLY VOLTAGE

**Typical Performance Curves**  $T_A = 25^\circ\text{C}$ ,  $V_{\text{SUPPLY}} = \pm 15\text{V}$ ,  $R_L = 1\text{k}\Omega$ ,  $C_L < 10\text{pF}$ , Unless Otherwise Specified (Continued)

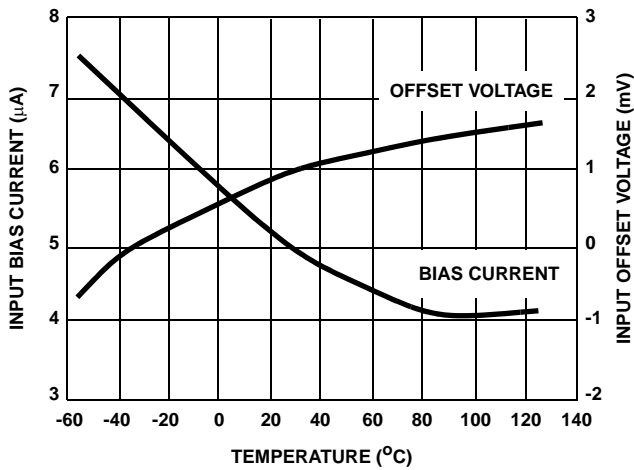


FIGURE 9. INPUT OFFSET VOLTAGE AND INPUT BIAS CURRENT vs TEMPERATURE

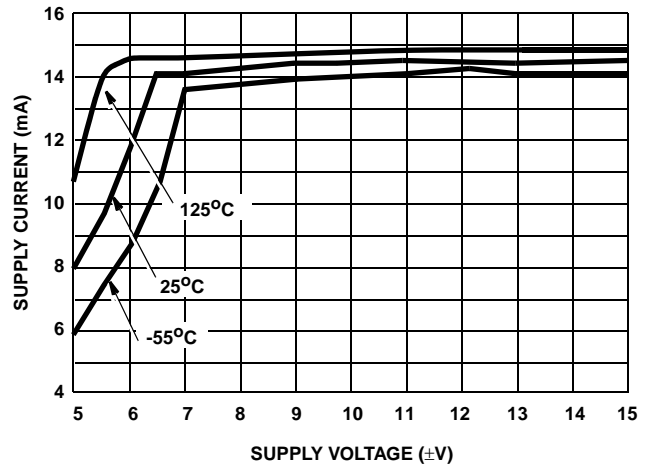


FIGURE 10. SUPPLY CURRENT vs SUPPLY VOLTAGE

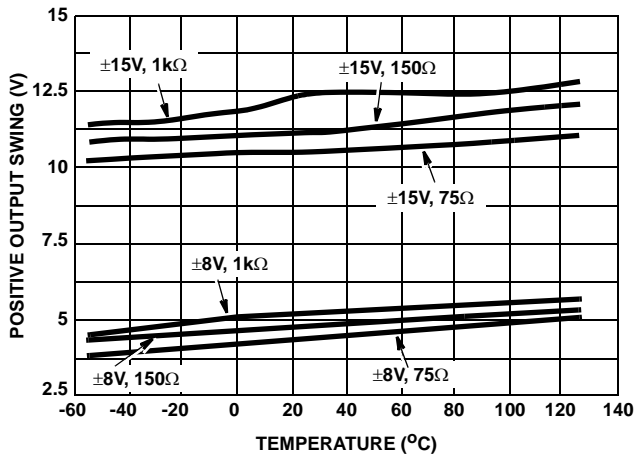


FIGURE 11. POSITIVE OUTPUT SWING vs TEMPERATURE

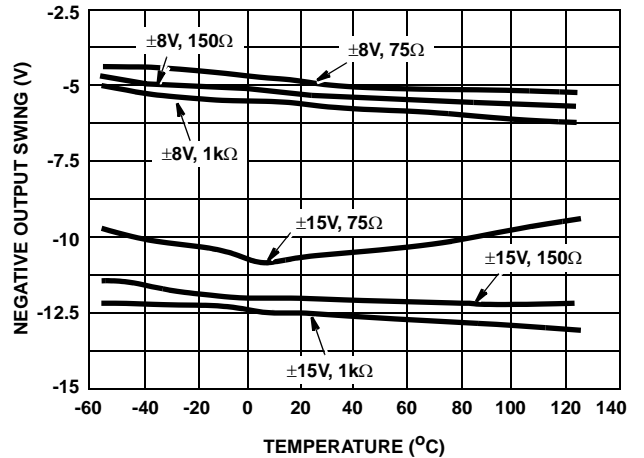


FIGURE 12. NEGATIVE OUTPUT SWING vs TEMPERATURE

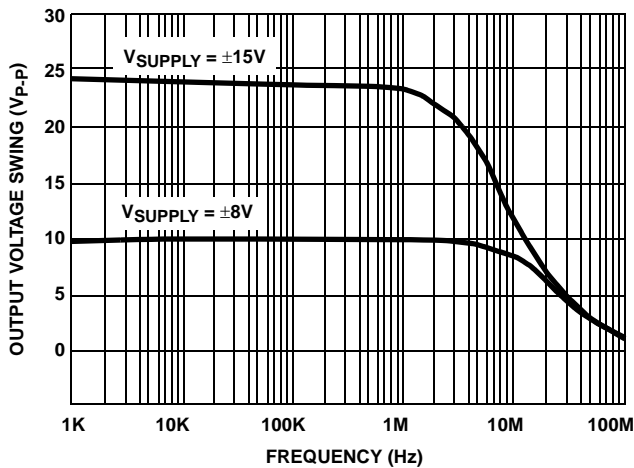


FIGURE 13. MAXIMUM UNDISTORTED OUTPUT SWING vs FREQUENCY

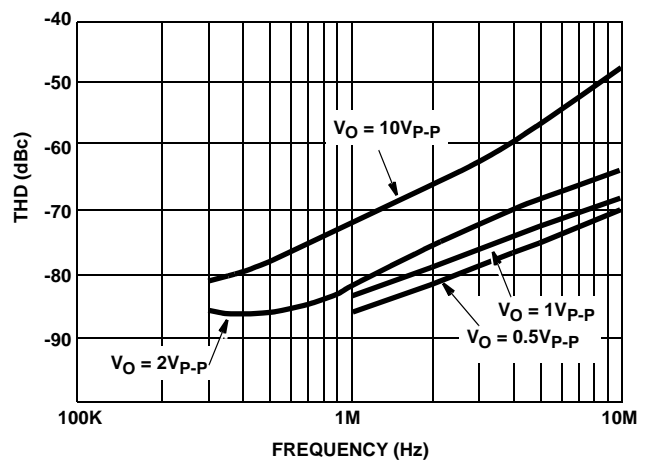


FIGURE 14. TOTAL HARMONIC DISTORTION vs FREQUENCY

**Typical Performance Curves**  $T_A = 25^\circ\text{C}$ ,  $V_{\text{SUPPLY}} = \pm 15\text{V}$ ,  $R_L = 1\text{k}\Omega$ ,  $C_L < 10\text{pF}$ , Unless Otherwise Specified (Continued)

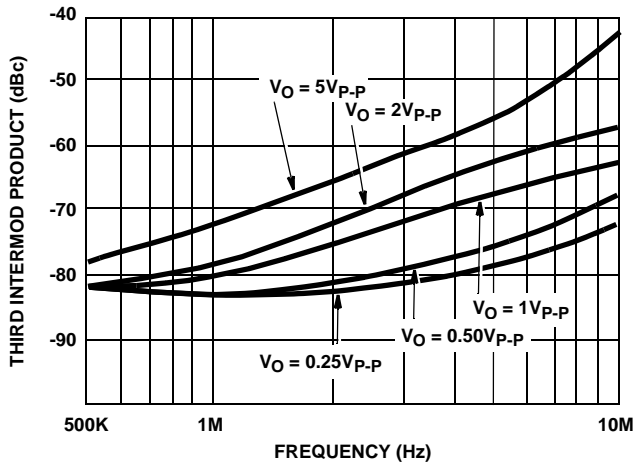


FIGURE 15. INTERMODULATION DISTORTION vs FREQUENCY (TWO TONE)

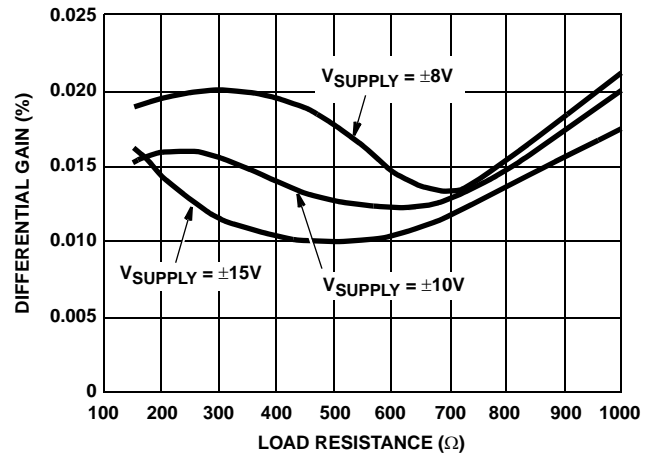


FIGURE 16. DIFFERENTIAL GAIN vs LOAD RESISTANCE

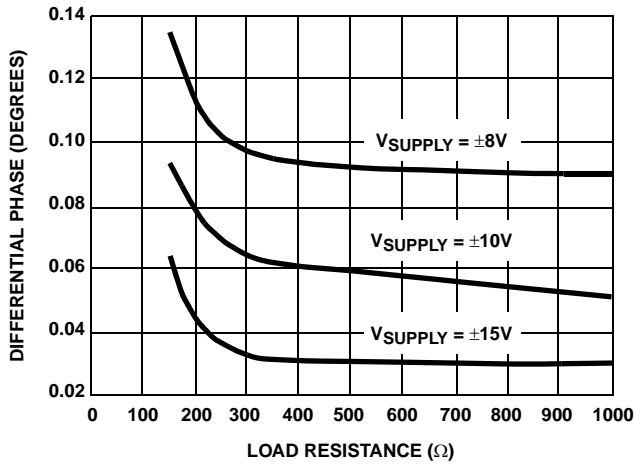


FIGURE 17. DIFFERENTIAL PHASE vs LOAD RESISTANCE

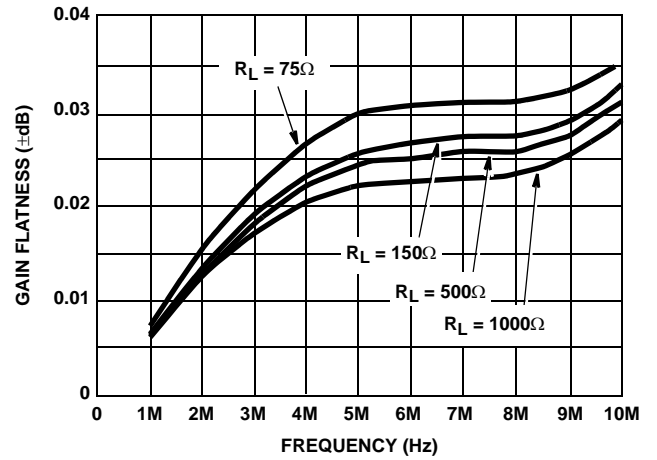


FIGURE 18. GAIN FLATNESS vs FREQUENCY ( $A_{VCL} = 2$ )

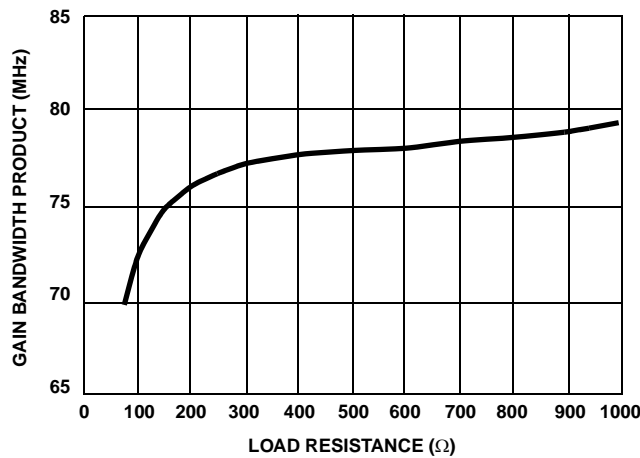


FIGURE 19. GAIN BANDWIDTH PRODUCT vs LOAD RESISTANCE



# HA-2842

## Die Characteristics

### DIE DIMENSIONS:

77 mils x 81 mils x 19 mils  
1960 $\mu$ m x 2060 $\mu$ m x 483 $\mu$ m

### METALLIZATION:

Type: Aluminum, 1% Copper  
Thickness: 16k $\text{\AA}$   $\pm$  2k $\text{\AA}$

### PASSIVATION:

Type: Nitride over Silox  
Silox Thickness: 12k $\text{\AA}$   $\pm$  2k $\text{\AA}$   
Nitride thickness: 3.5k $\text{\AA}$   $\pm$  1k $\text{\AA}$

### SUBSTRATE POTENTIAL (POWERED UP):

V-

### TRANSISTOR COUNT:

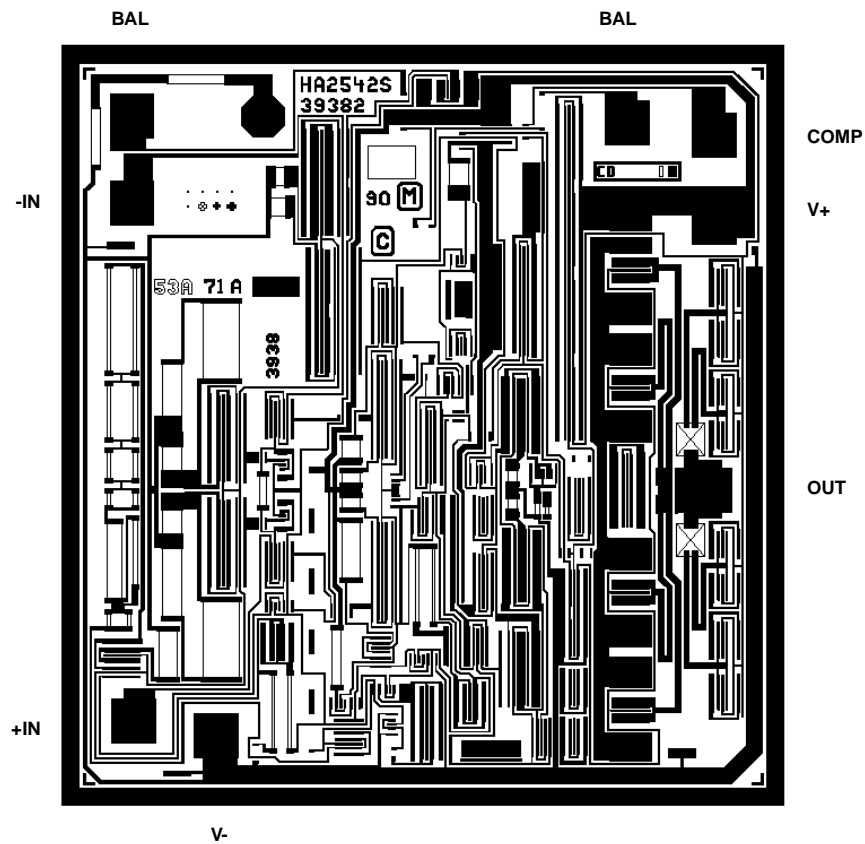
58

### PROCESS:

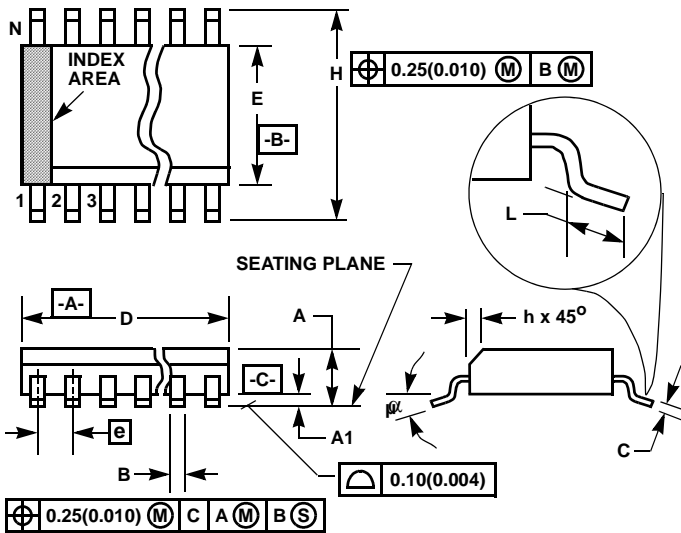
High Frequency Bipolar Dielectric Isolation

## Metallization Mask Layout

HA-2842



**Small Outline Plastic Packages (SOIC)**



**M8.15 (JEDEC MS-012-AA ISSUE C)  
8 LEAD NARROW BODY SMALL OUTLINE PLASTIC  
PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0532	0.0688	1.35	1.75	-
A1	0.0040	0.0098	0.10	0.25	-
B	0.013	0.020	0.33	0.51	9
C	0.0075	0.0098	0.19	0.25	-
D	0.1890	0.1968	4.80	5.00	3
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		-
H	0.2284	0.2440	5.80	6.20	-
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	8		8		7
$\alpha$	0°	8°	0°	8°	-

**NOTES:**

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

Rev. 0 12/93

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